Computational modelling of $Ti_{50}Pd_{50-x}Cu_x$ ($0 \le x \le 25$) high temperature shape memory alloys

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Introduction

Titanium-based alloys in particular Ti₅₀Pd₅₀ are being developed for high temperature applications. The Ti₅₀Pd₅₀ alloy has a potential for high temperature shape memory applications due to its martensitic transformation capability from B2 to B19 at 823 K [1]. This alloy exists as a high temperature phase (austenite phase) which has a simple cubic B2 while at low temperature is known as the martensite phase with an orthorhombic B19 structure [2]. Previous studies indicated that B2 TiPd is unstable displaying a negative C' at 0 K [3]. Consequently, the binary Ti₅₀Pd₅₀ alloy has no strength for use in actuators and aeronautic industry and ternary alloys need to be established to improve their properties Then, alloying with Cu is an attempt to improve their strength at 0 K as it has extraordinary properties such as corrosion resistance and high thermal conductivity. In this study, ternary alloying of Ti₅₀Pd₅₀ with Cu have been performed using DFT approach to investigate the thermodynamic and mechanical stability to deduce their potential in HT application.

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3,18

3,17

(y) 3,16 3,15

ö 3,14

3,13

attice

(a)

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at. % Cu

The heat of formation is determined by expression: $\Delta H_f = E_C - \sum_i x_i E_i$

Figure 1 (a): It is clear that the lattice parameter

attributed to the small radius of Cu compared to Pd.

decreases as Cu content is increased, this is

For a structure to be stable, the heat of formation must have the lowest negative value ($\Delta H_f < 0$). Figure 1 (b): It is clearly seen that the heat of formation decreases as the concentration of Cu is increased. At 6.25 at. % Cu, the Δ Hf is the lowest which implies thermodynamically stable compared to other Cu compositions such as 18.75 and 25..

Figure 1: (a) Lattice parameter, a (Å) and (b) heats of formation of the B2 Ti₅₀Pd_{50-x}Cu_x ($0 \le x \le 25$) ternary SMAs.

Elastic properties



Figure 3: Simulated (a) Bulk (B), Shear (G), Young 's modulus and (b) The B/G ratio, Poisson 's ratio as a function of atomic percent Cu for $Ti_{50}Pd_{50-x}Cu_x$ ($0 \le x \le 25$) SMAs.

Figure 3 (a): The bulk modulus decreases minimally with an increase in Cu concentration. Ti₅₀Pd_{43,75}Cu_{6,25} appears to be the hardest due to the highest bulk modulus as compared to other compositions. The G and E is greater than above 18 at. % Cu which indicate that the structure is less compressible and stiffer.

Ductility condition:

The Pugh (B/G) > 1.75 [10] and Poisson (σ)> 0.26 [11] is regarded as ductile otherwise brittle.

In Figure 3 (b), the B/G ratio >1.75 except for 6.25 at. % Cu (condition of ductility). In the case of Poisson 's ratio, the ductility is observed for $(0 \le x \le 25)$ as the ratio is greater than 0.26.

Phonon dispersion curves



[&]quot;Simulate, Know Materials"